

# Announcement and Call for Papers

# ICEP2010

International Conference on Electronics Packaging

**May 12 -14, 2010**

**Sapporo Convention Center, Hokkaido, Japan**

**Sponsored by JIEP, and IEEE CPMT Society Japan Chapter**

## Technical Topics for Conference Papers

### Sessions and Keywords:

#### 1. Advanced Packaging

Area array packages, SiP, PoP, PiP, wafer level packaging, system integration, LCD modules, MCM, and System on Package

#### 2. Substrate

Laminates, interposers, fine pitch, build-up substrates, FPC (Flexible Printed Circuits), embedded, conductive paste, thin core, coreless, low CTE, and thin film wiring

#### 3. Design, Modeling, and Reliability

Signal integrity, power integrity, thermal management, high speed board design, reliability, failure analysis, testing, evaluation, and EDA

#### 4. Manufacturing and Process

Flip chip, plating, inkjet, process control, equipment, thin films, underfills, encapsulation, molding, and fluxes

#### 5. Interconnection

Flip chip, wire bonding, soldering, bump formation, NCF/NCP, ACF/ACP and fluxless joining

#### 6. Optoelectronics

Photonic devices, optical fibers, wave guides, optical interconnects, transceivers, connectors, LD/PD, LED, OE/EO, TOSA/ROSA, WDM, and optical wiring boards

#### 7. Printed Electronics

Inkjet, screen printing, conductive wiring, insulation, printed organic TFT, and device applications

#### 8. 3D and TSV

Silicon stacking, Chip on Chip, Chip on Wafer, Wafer on Wafer, TSV, via formation and filling, wafer thinning, wireless interconnection, and 3D LSI design and CAD system

#### 9. MEMS/Sensor

MEMS/Sensor devices, process, assembly and packaging, system integration, and MOEMS

#### 10. Self-Organization/Self-Assembly

Nano materials/devices by self-organization/self-assembly, Dissipative structures, hierarchical structures, bottom-up manufacturing Bio-mimetic, nature-oriented processes/design/applications

#### 11. Emerging Technologies

Nano technology, and organic semiconductors

#### 12. RF

RFID, high frequency devices, packaging, filters, EMI, EMC, and antennas

#### 13. Automotive Electronics

Power devices, power electronics, ECU, sensors, lead free solder, and wire harness

#### 14. Energy and Environment

PV, lead free, fuel cells, power electronics, and power devices

#### 15. Others

Market trends, environmentally conscious product and processes, and cost analysis

## Abstract and Paper Submission:

300-word abstract to be submitted to the secretariat by e-mail or fax by ~~November 15~~ December 12, 2009

Notification of acceptance by the middle of December 2009 (Postponed)

Final manuscript to be submitted by March 19, 2010

## Registration Fees:

Speakers: 40,000 yen (including reception and the proceedings)

Students: 5,000 yen (including the proceedings)

## Organizing Committee:

General Chair: M. Mori, Toshiba

Vice General Chairs: Y. Orii, IBM Japan and M. Nakamura, Hitachi

## Contact:

Secretariat of ICEP 2010

JIEP (Japan Institute of Electronics Packaging)

E-mail: [icep2010@jiep.or.jp](mailto:icep2010@jiep.or.jp)

URL: <http://www.jiep.or.jp/icep/>

# Abstract Submission Form

Please attach this form to your abstract

**Paper Title:**

---



---

**Session Preference:**

Primary Session Name :

---

Secondary Session Name :

---

Keywords :

---

Presentation Style : Oral Poster (Student only)

Submitted papers may be assigned to other/additional sessions at the discretion of the technical program committee.  
You may select up to five keywords.

**Author Information:**

Prefix: Prof. [ ], Dr. [ ], Ms. [ ], Mr. [ ] / [ ] Student  
First Name Last Name

Name:

---

Membership No.: JIEP IEEE

---

Company or Institution:

---

Department or Division:

---



---

Address:

---



---

Zip Code: Country:

---



---

Phone: Fax:

---



---

E-mail:

---

**Publication Schedule:**

300-word abstract submission deadline: ~~November 15~~ December 12, 2009 by e-mail or fax (Postponed)

Notification of acceptance: middle of December 2009

Submission of final manuscript: March 19, 2010

Please send your abstract and this form by e-mail or fax.  
 Fax: +81-3-5310-2011, E-mail: icep2010@jiep.or.jp